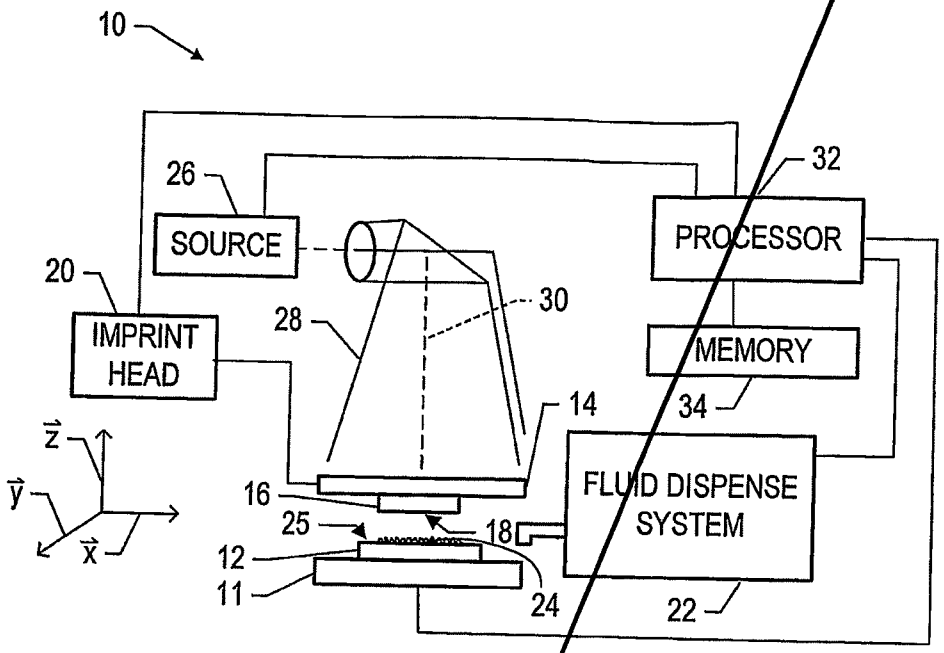


FIG. 1
(Prior Art)

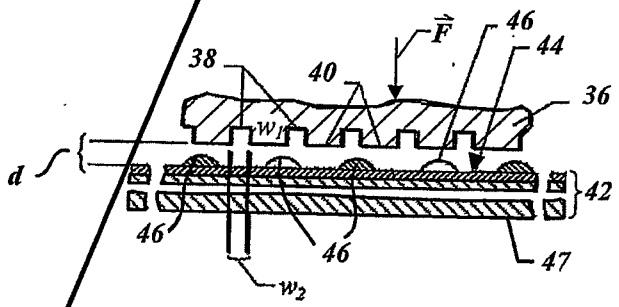


FIG. 2

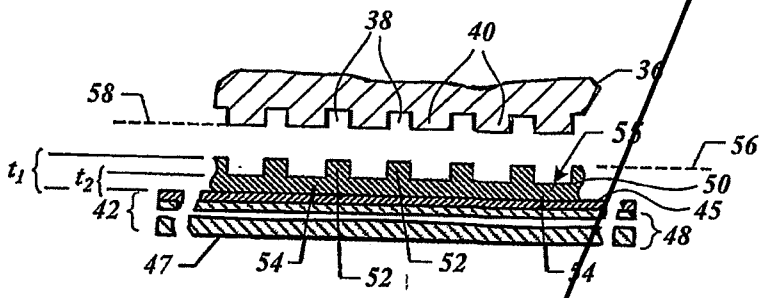


FIG. 3

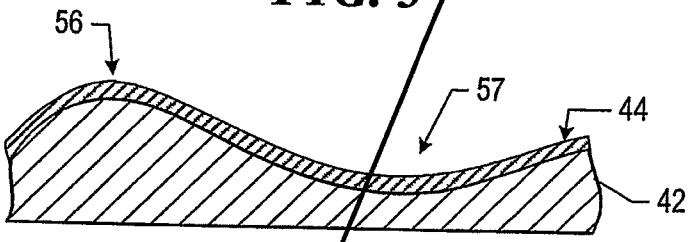


FIG. 4

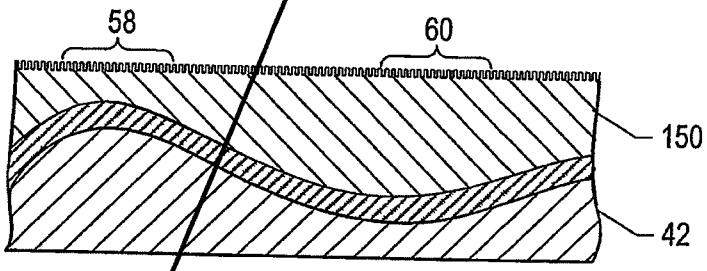


FIG. 5

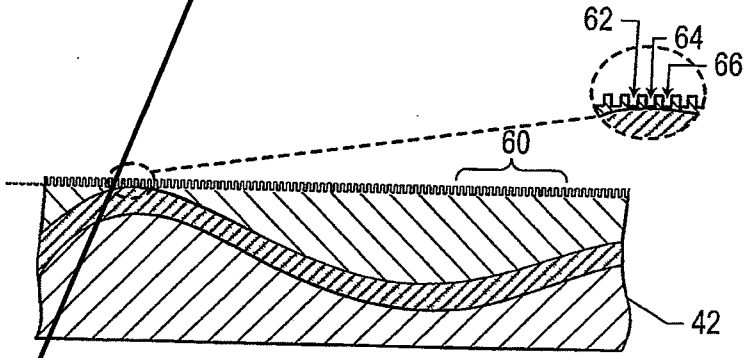


FIG. 6

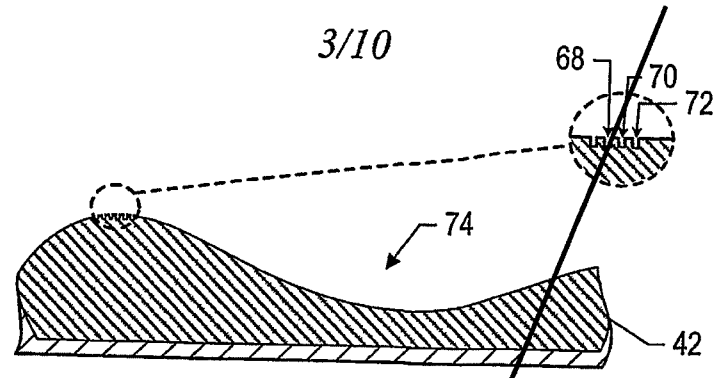


FIG. 7

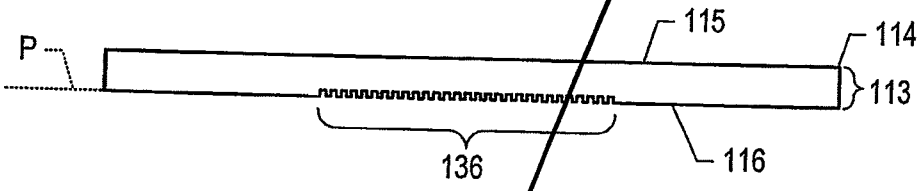


FIG. 8

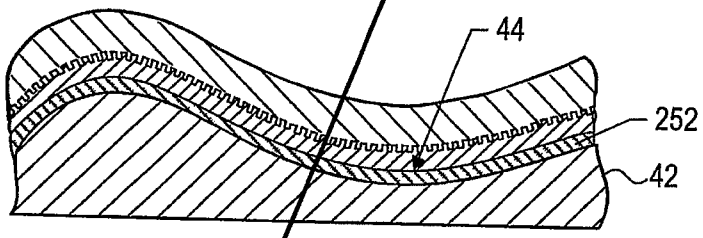


FIG. 9

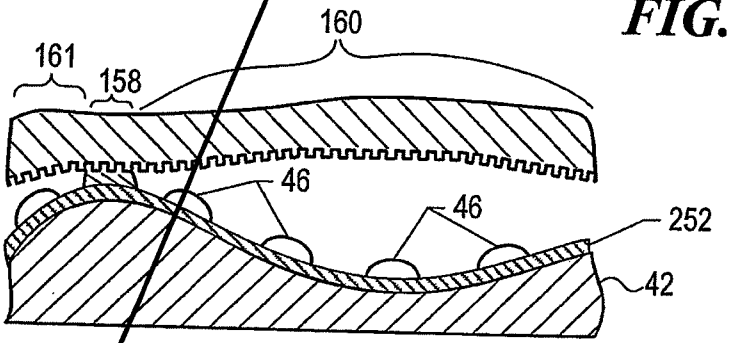


FIG. 10

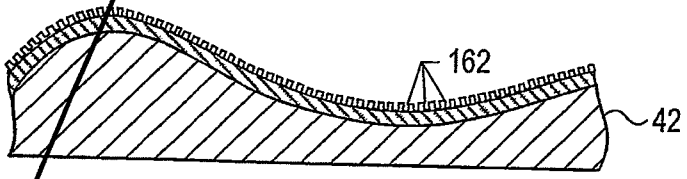


FIG. 11

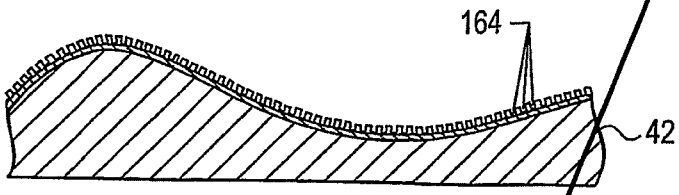


FIG. 12

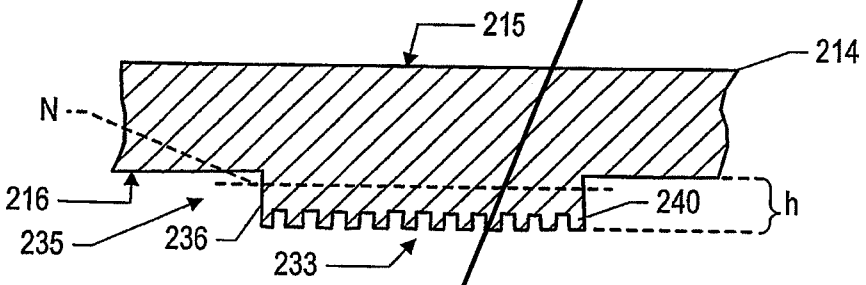


FIG. 13

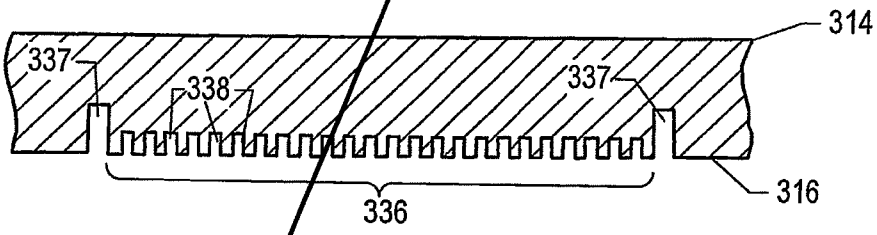


FIG. 14

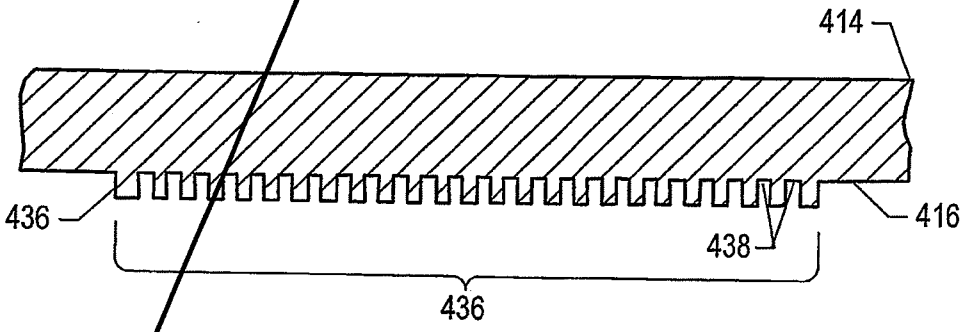


FIG. 15

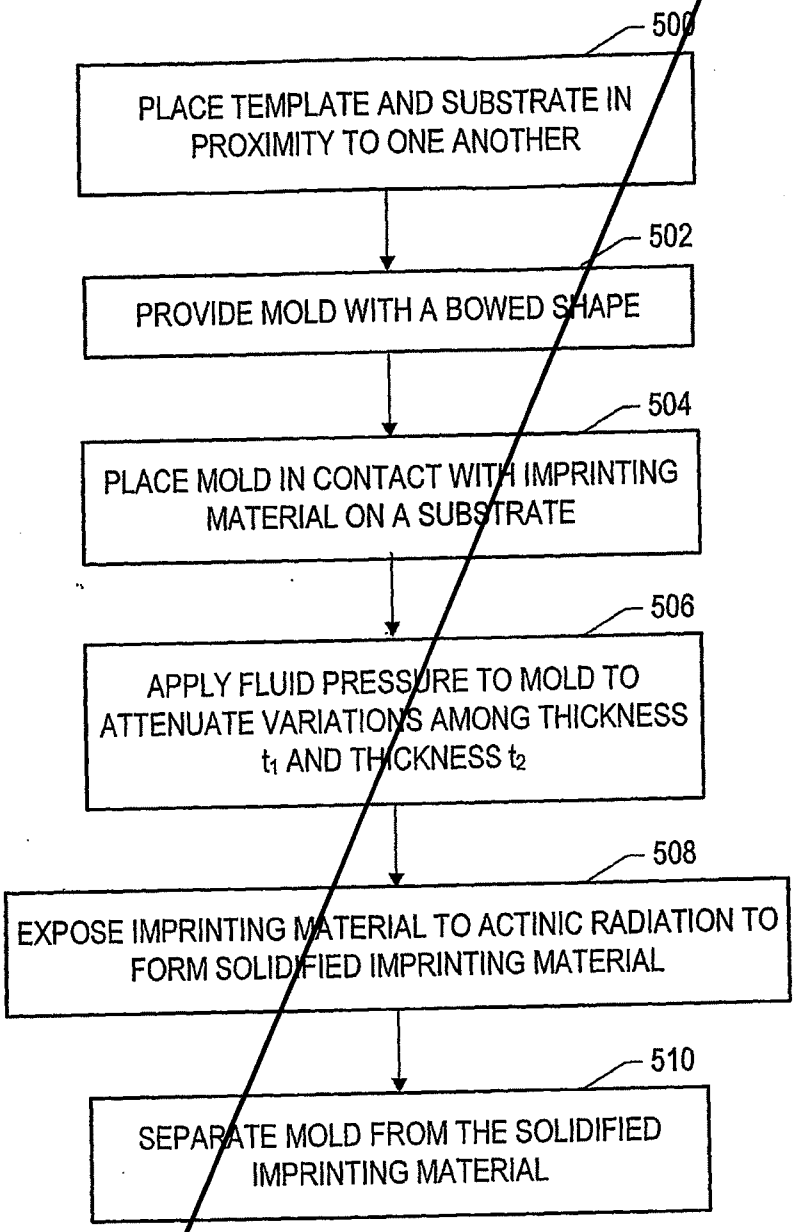

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PROVIDE MOLD WITH A BOWED SHAPE
504
PLACE MOLD IN CONTACT WITH IMPRINTING MATERIAL ON A SUBSTRATE
506
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508
EXPOSE IMPRINTING MATERIAL TO ACTINIC RADIATION TO FORM SOLIDIFIED IMPRINTING MATERIAL
510
SEPARATE MOLD FROM THE SOLIDIFIED IMPRINTING MATERIAL

FIG. 16

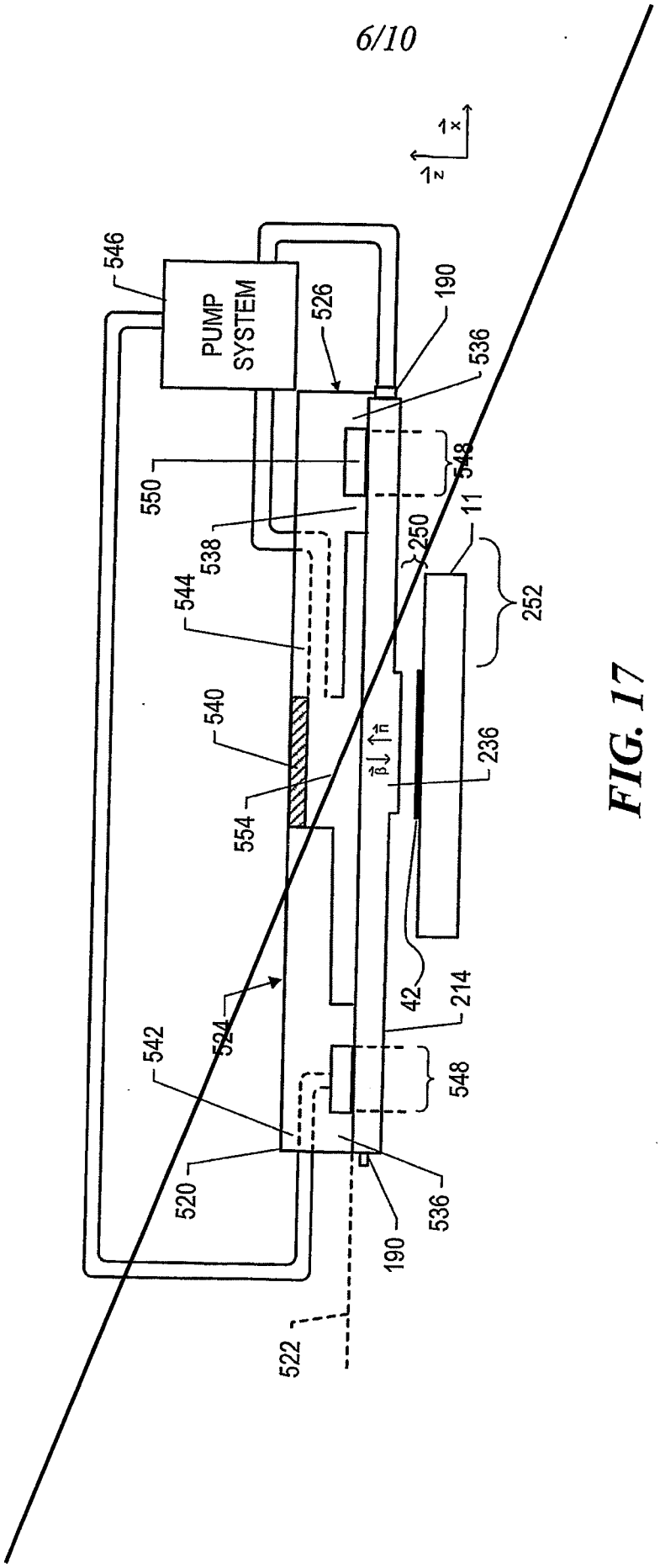

PUMP SYSTEM
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FIG. 17

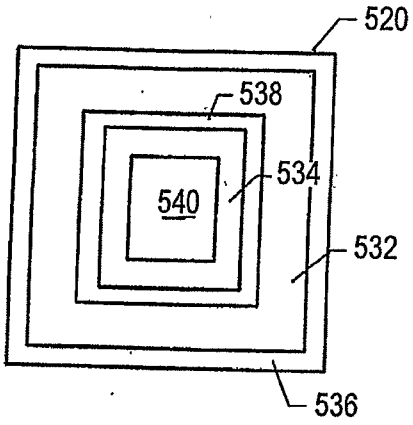

520
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FIG. 18

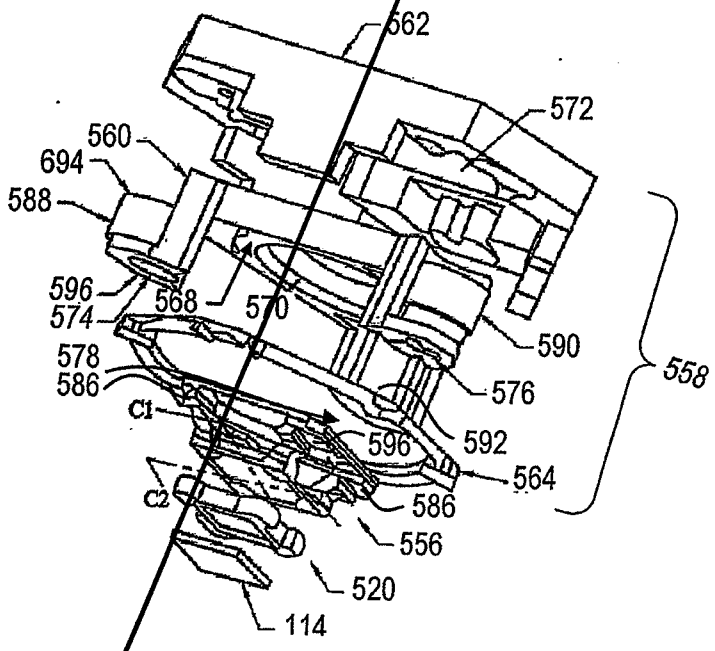

562
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114
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FIG. 19

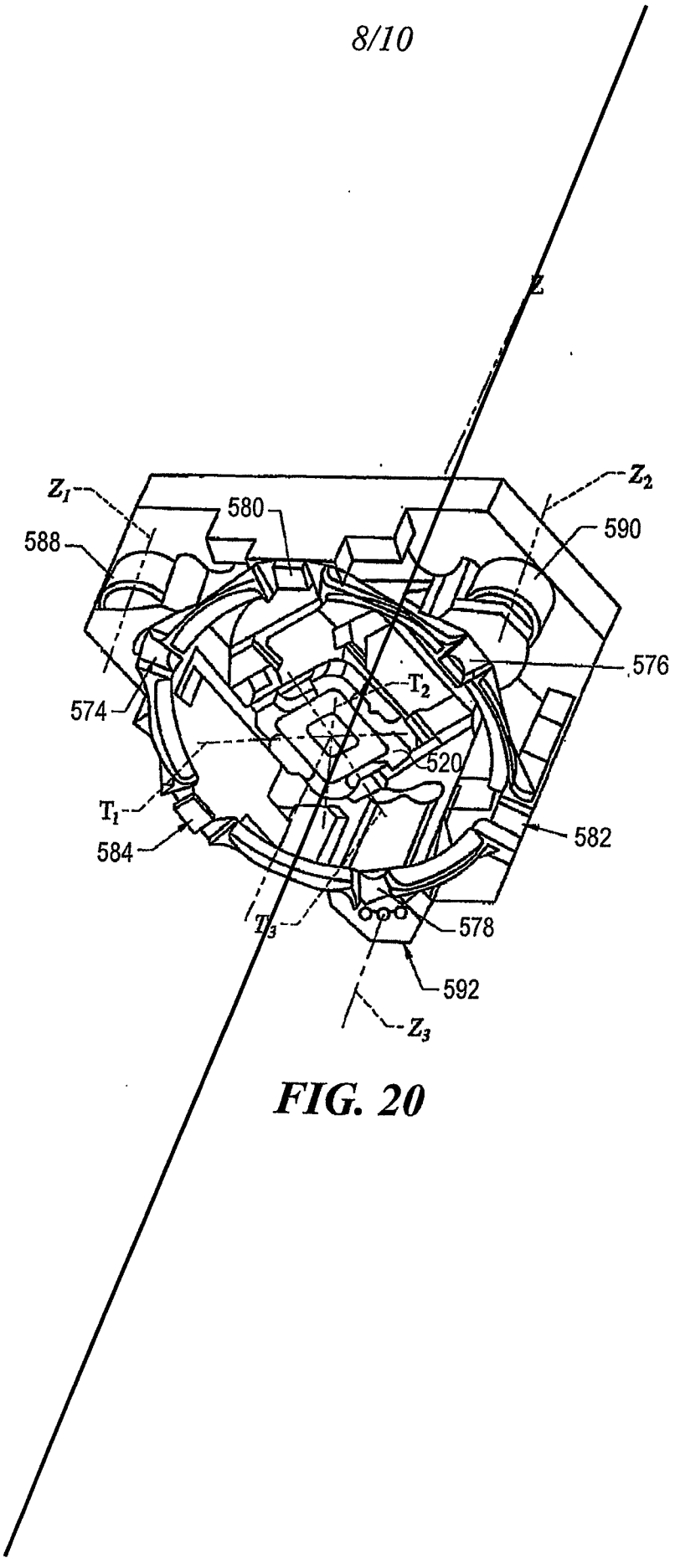


FIG. 20

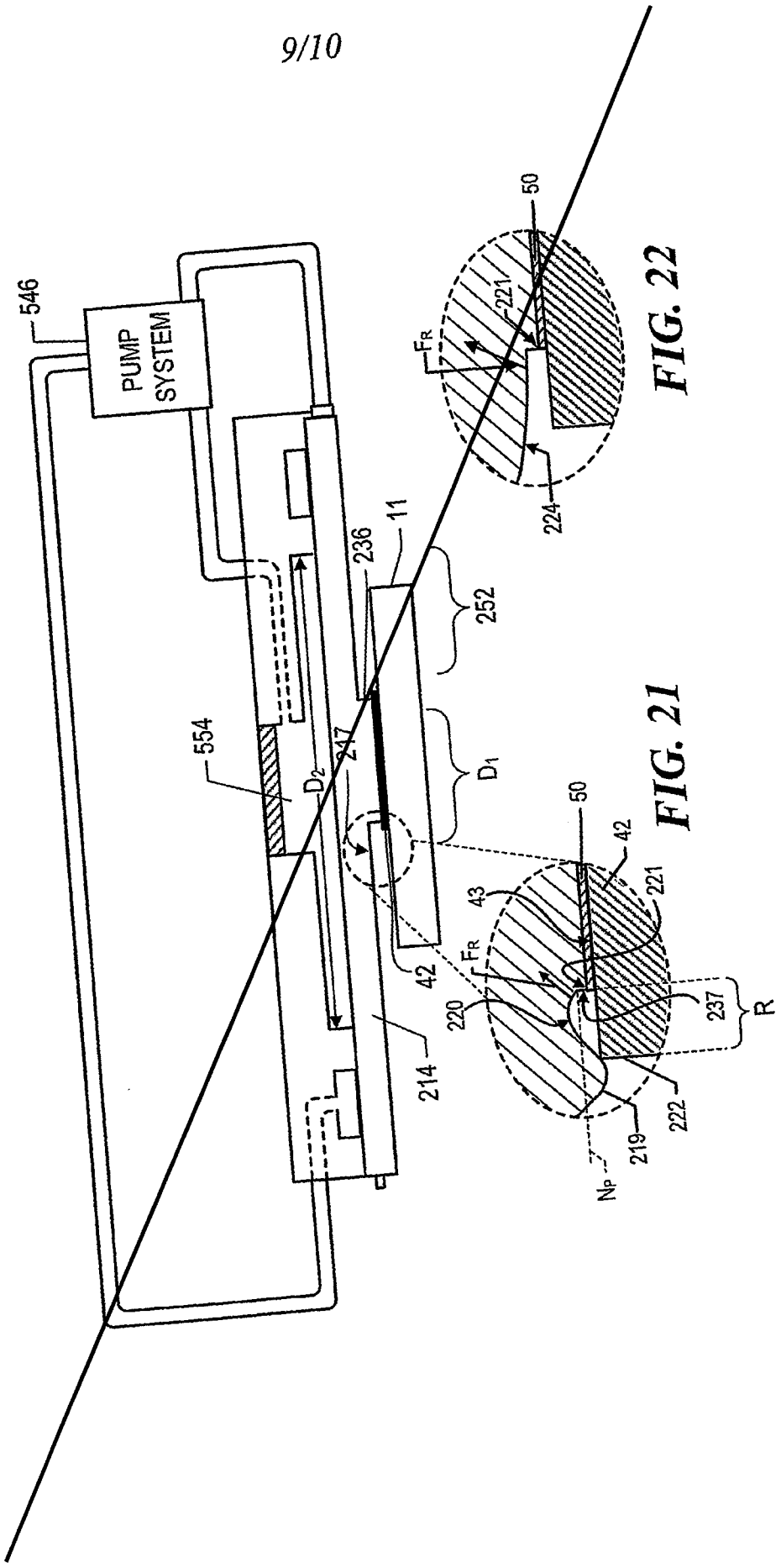

546
PUMP SYSTEM
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236
11
214
50
221
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224
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237
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FIG. 22

FIG. 21

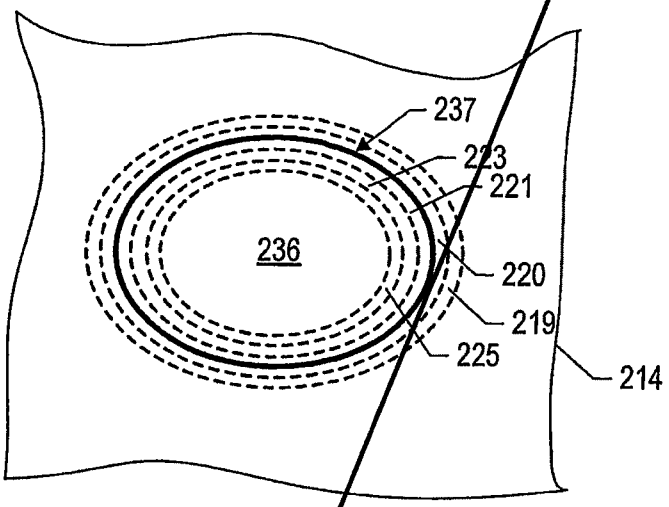


FIG. 23

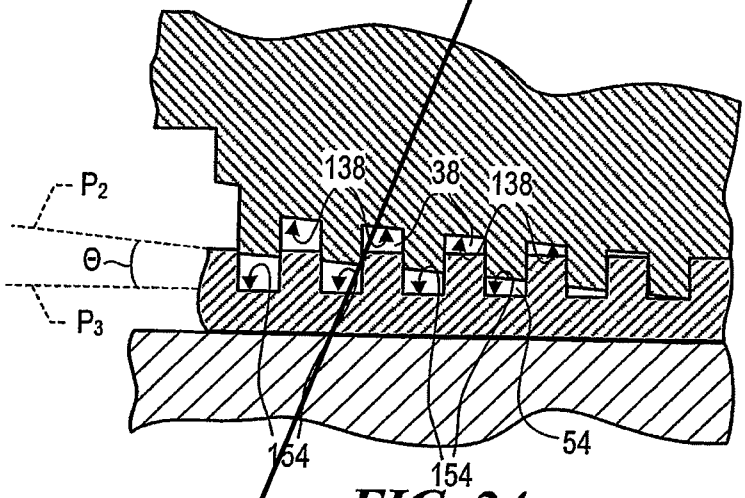


FIG. 24

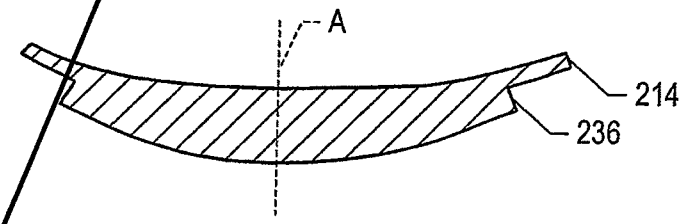


FIG. 25

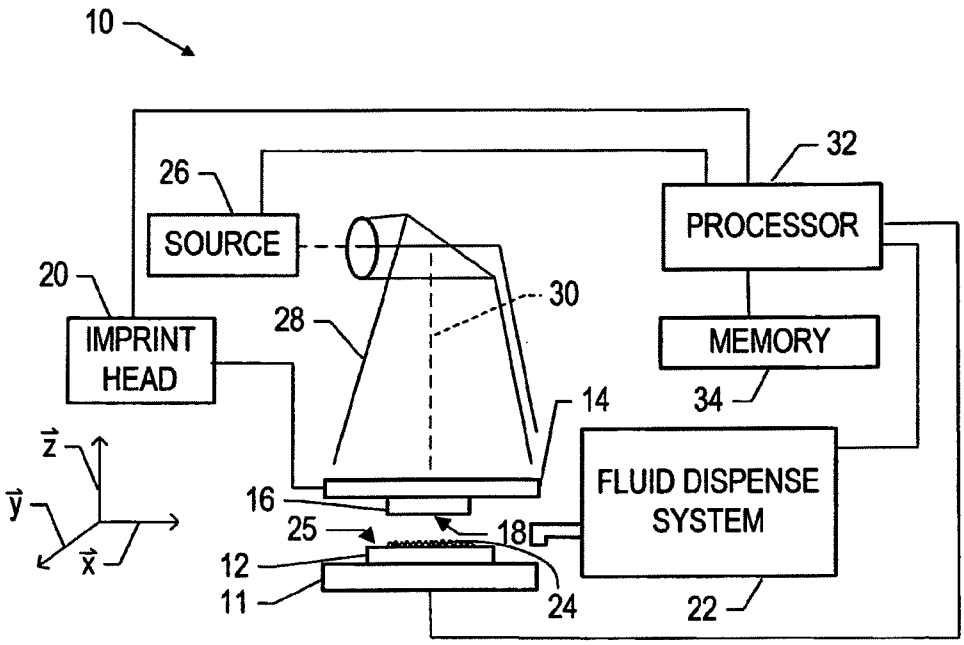


FIG. 1
(Prior Art)

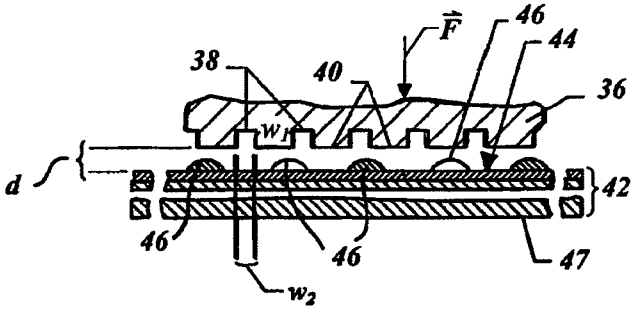


FIG. 2

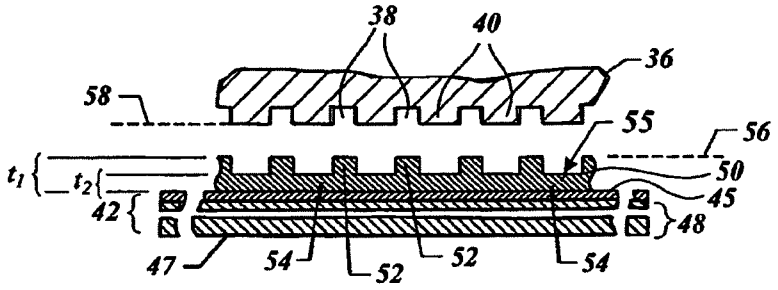


FIG. 3

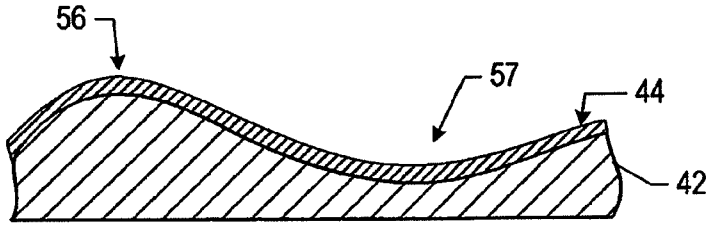


FIG. 4

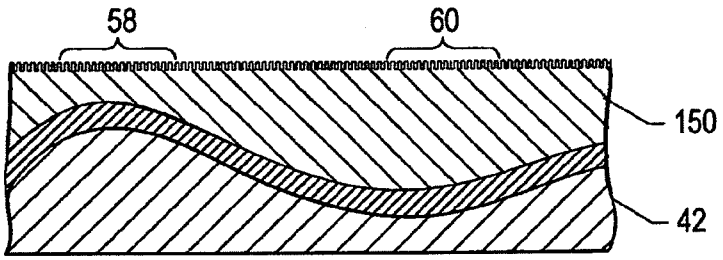


FIG. 5

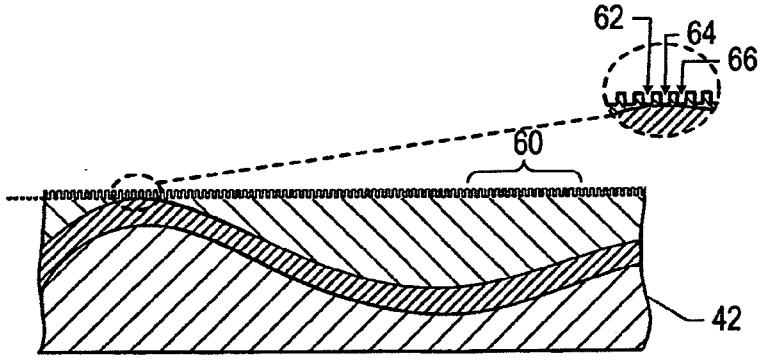


FIG. 6

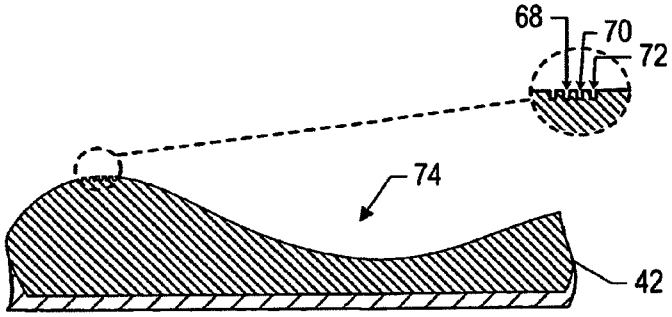


FIG. 7

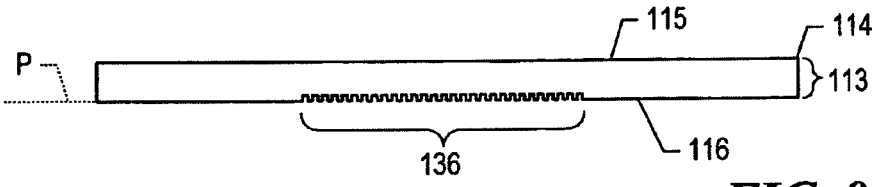


FIG. 8

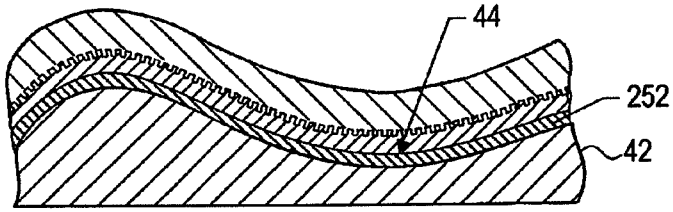


FIG. 9

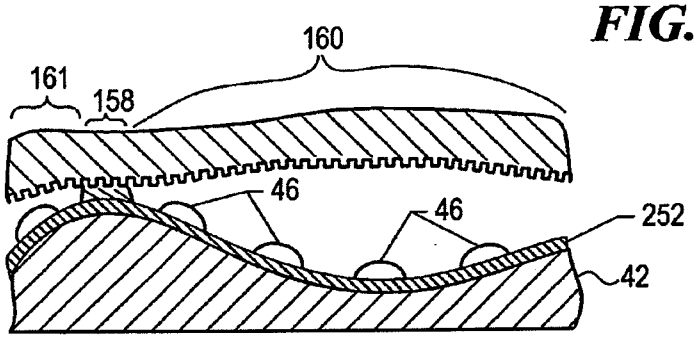


FIG. 10

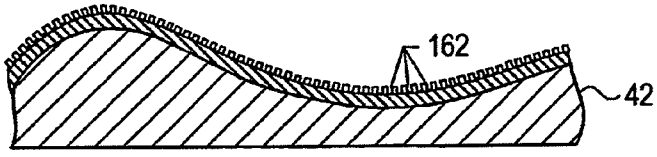


FIG. 11

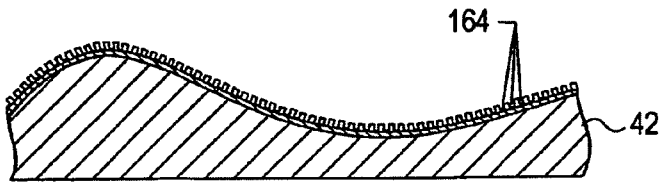


FIG. 12

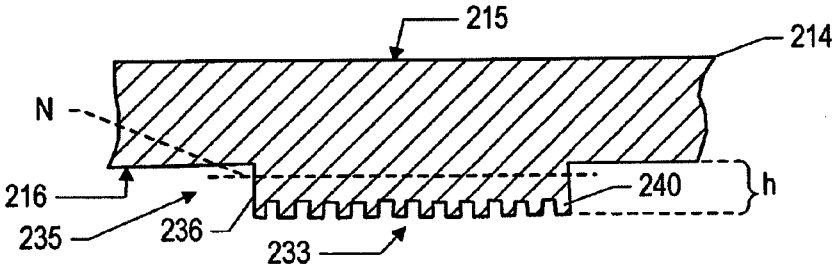


FIG. 13

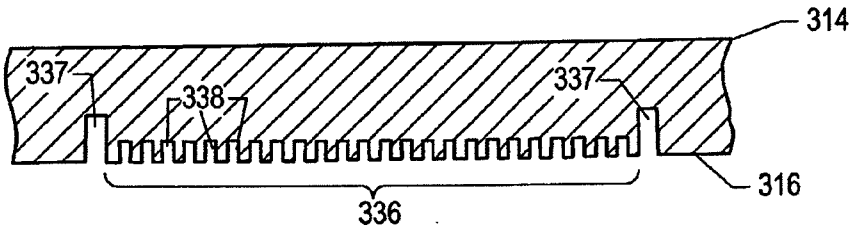


FIG. 14

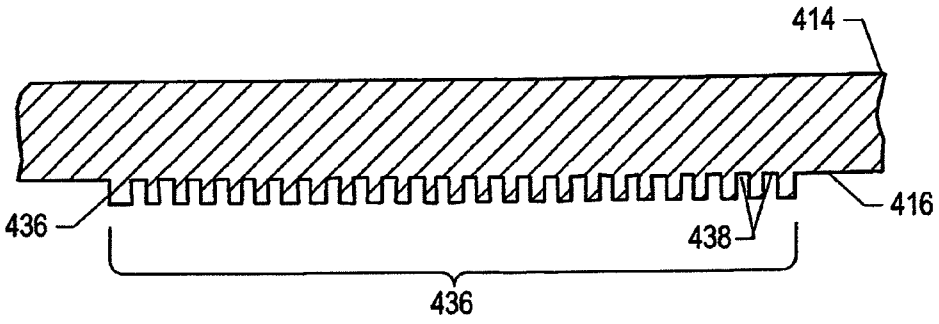


FIG. 15

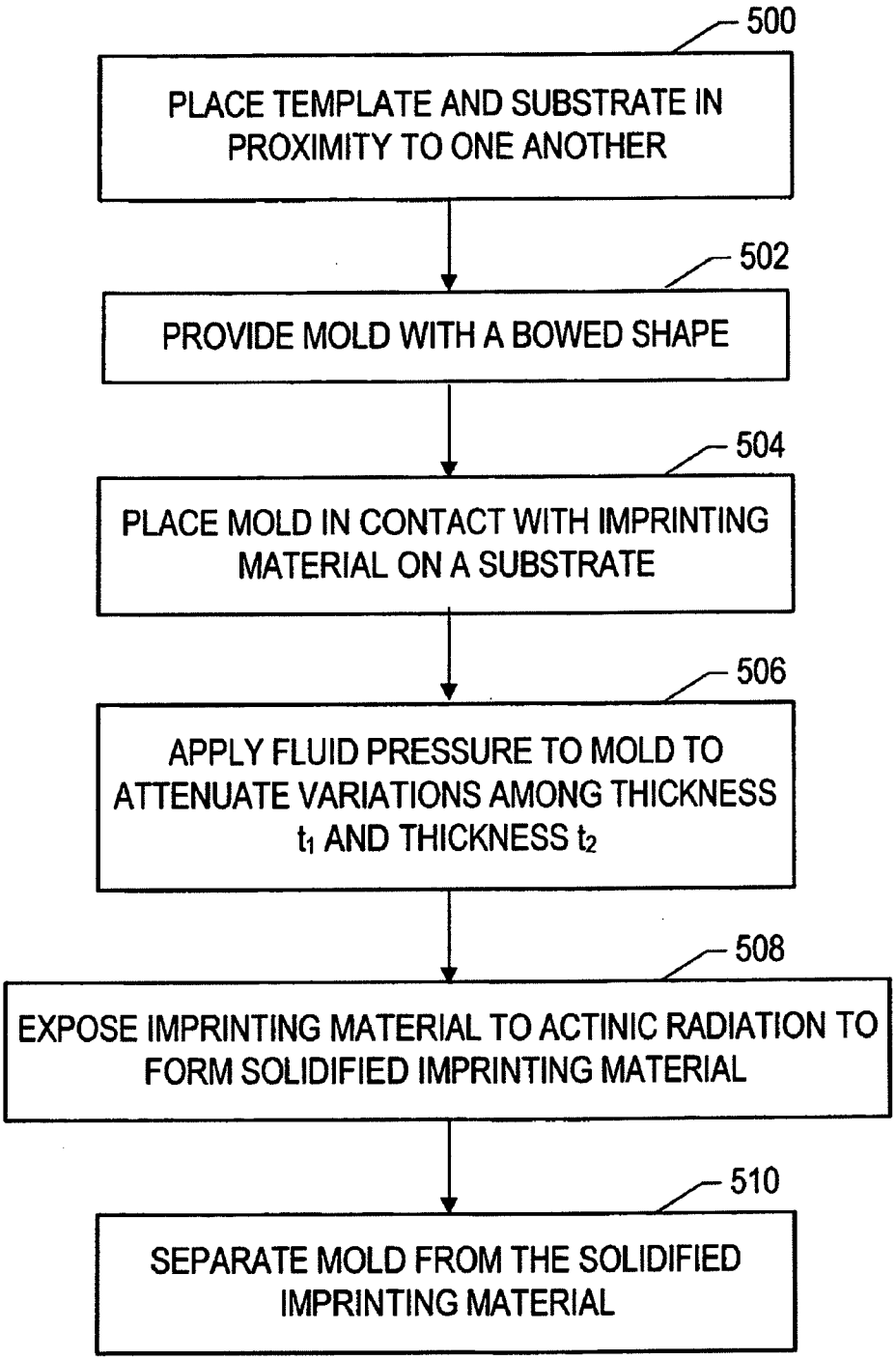

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FIG. 16

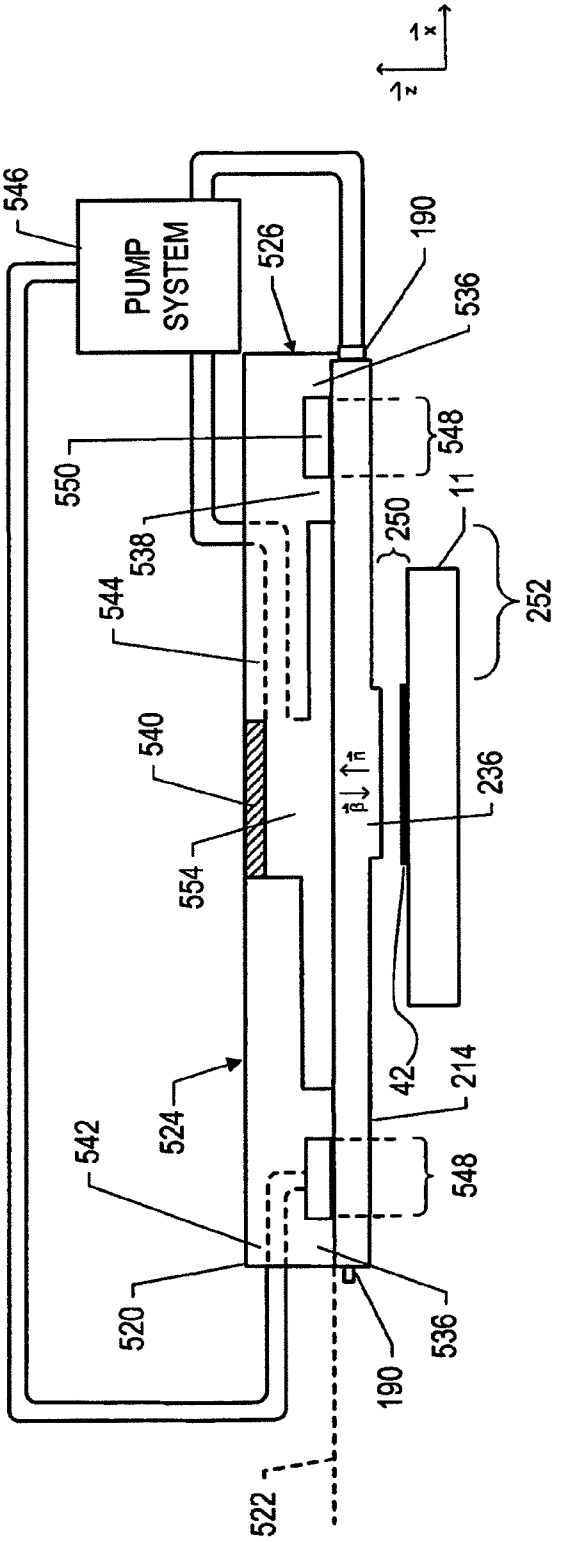

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FIG. 17

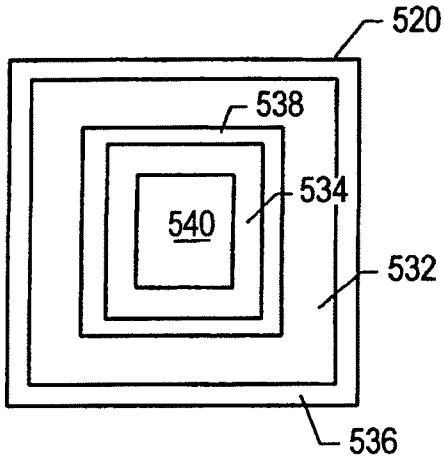

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FIG. 18

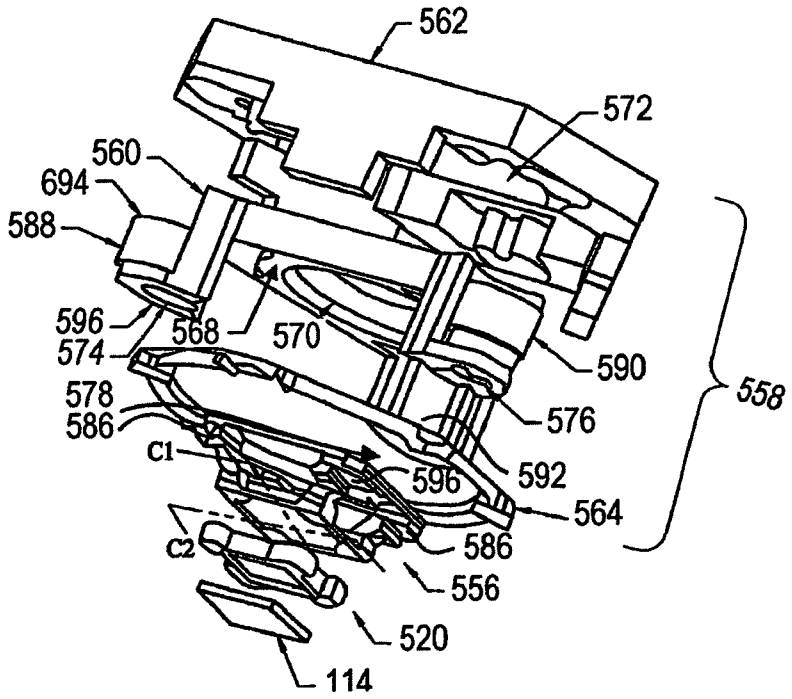

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FIG. 19

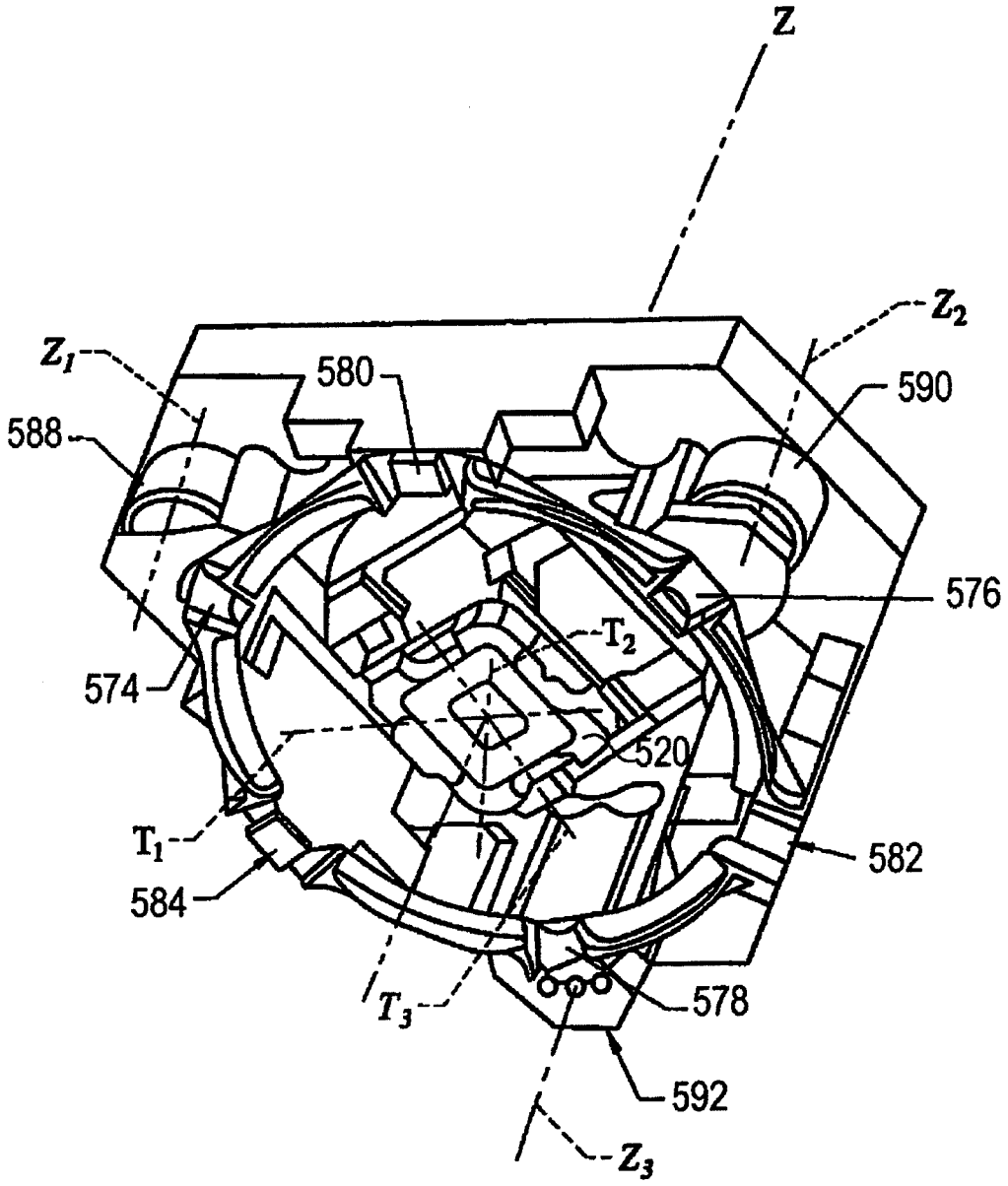


FIG. 20

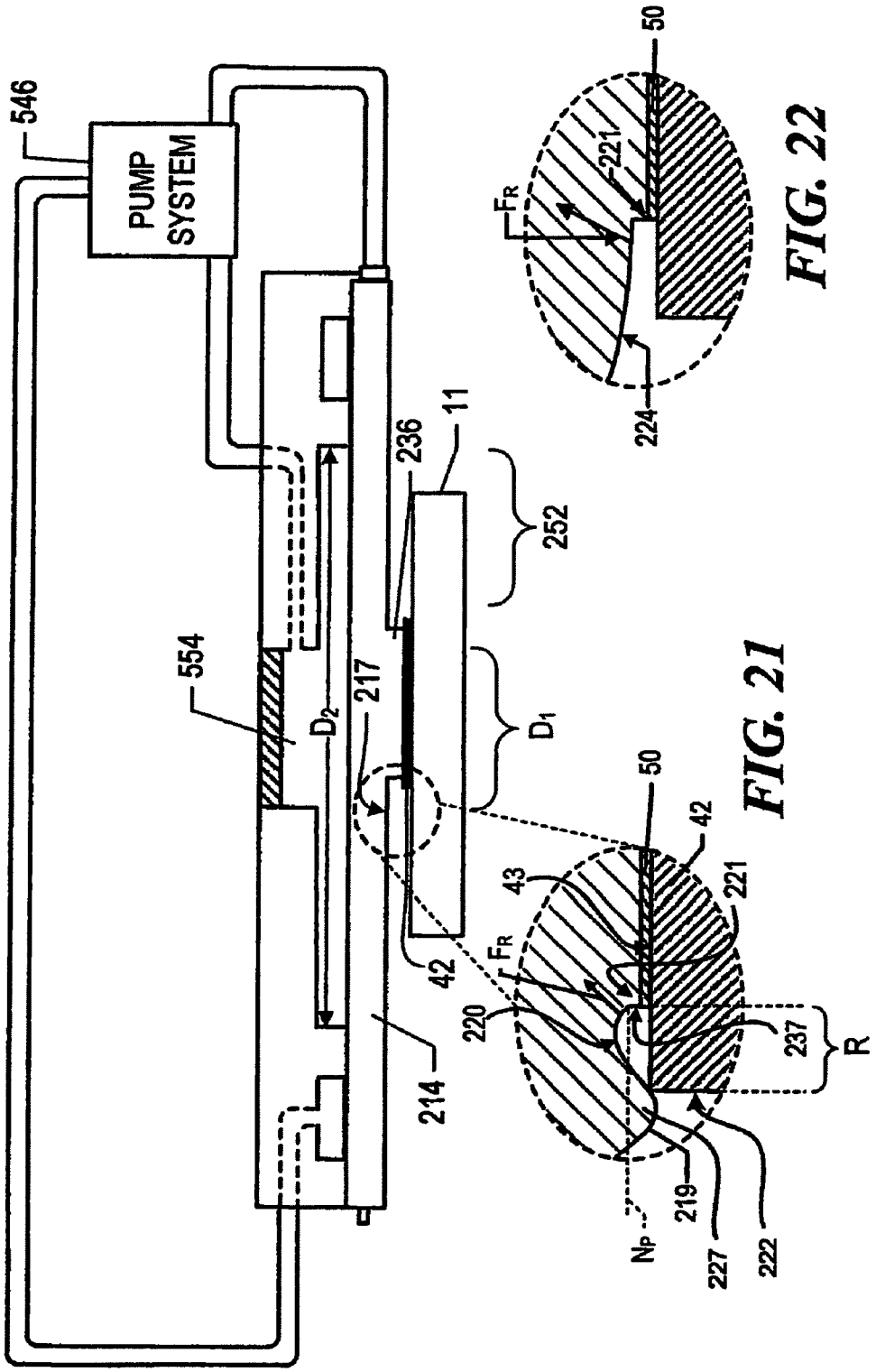

546
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FIG. 21

FIG. 22

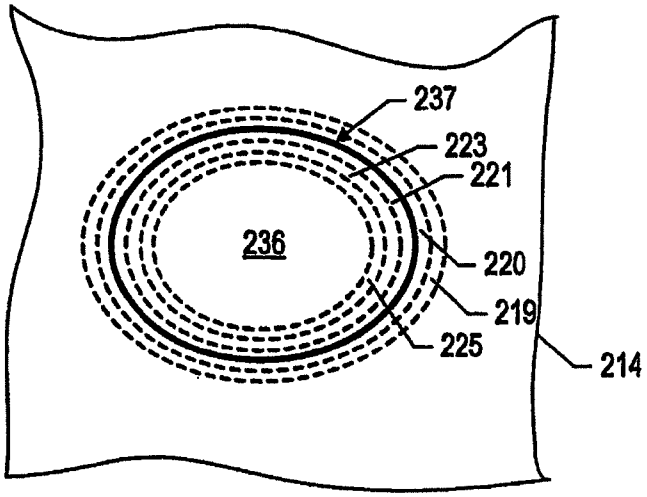


FIG. 23

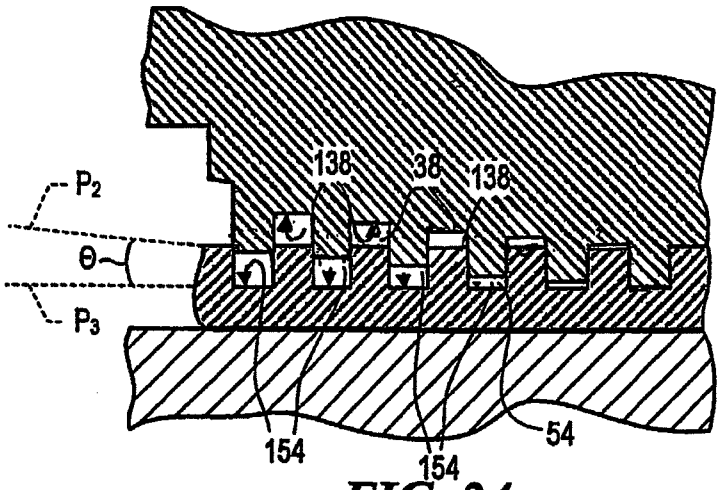


FIG. 24

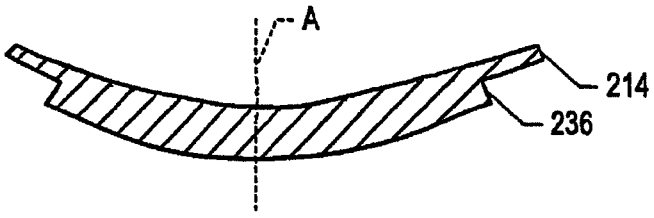


FIG. 25